

高周波対応として、『矩形』の配線断面と、『平滑』な配線表面により導体損失を大幅に低減

Reducing conductor loss by ideal rectangular cross-sectional shape and surface smoothness of copper wiring for high frequency compatible



セミアディティブプロセス対応 高速伝送FPC用基材 新シード・ポリイミドフィルム

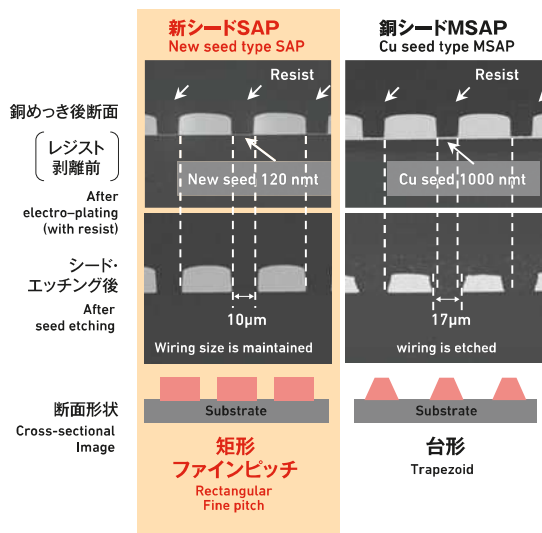
High speed transmission FPC substrate using Semi-Additive Process
New seed polyimide film

特長 Features

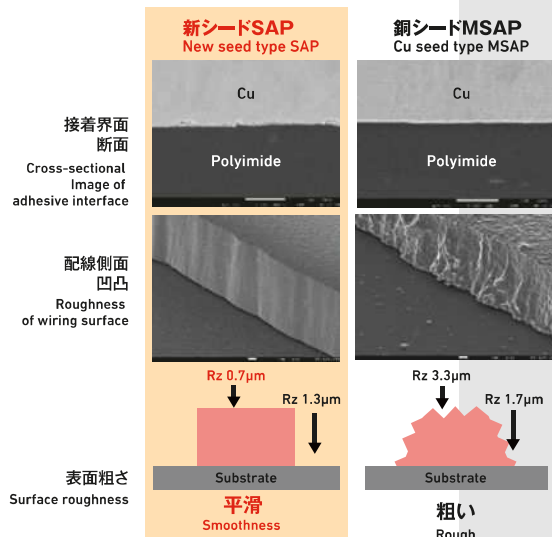
- 配線の断面形状が理想的な『矩形』かつ配線の『平滑性』を実現
Realization of ideal rectangular cross-sectional shape and surface smoothness on copper wiring
- 設計通りの配線間距離で『ファインピッチ化』に対応
Fine pitch wiring with exactly the same wiring width as design drawing
- 高周波数帯における伝送特性が従来工法と比較して向上
Improving transmission characteristics in the high frequency band as compared with conventional method
- 平滑な基材との接合界面で『銅配線の密着力』が高い(非粗化表面)
High adhesive strength of copper wiring on a smooth adhesive interface

特性 Properties

配線の断面形状 (Cross-sectional image of wiring)



配線の平滑性 (Roughness of copper wiring)



用途 Application

■ FPC (Flexible Printed circuit)、COF (Chip On Film)

- 低損失の高周波伝送配線
Low Loss Transmission Lines for High Frequency
- 高品質アンテナ
High Quality Antenna
- 高精度配線・高密度配線
High Density and High Accuracy Printed Circuit